

CONFIRMING METHOD

ABSTRACT OF THE DISCLOSURE

Two linear processing marks are formed on a face side of a metal foil of a confirmation wafer, and a laser beam is applied to the confirmation wafer at a reference position intermediate between the linear processing marks to form a modified layer in a base member of the confirmation wafer. Though the modified layer formed in the base member is difficult to visually recognize, the linear processing marks can easily be visually recognized by an operator as they are clearly formed on the face side of the metal foil. Therefore, the operator can easily grasp the position of the modified layer, i.e., the position where the laser beam was applied to form the modified layer in the base member on the basis of the linear processing marks. Inasmuch as the operator can acquire the positional relationship between the position where the laser beam was applied and surface damage spots formed by the laser beam that has reached the face side of the base member, the operator can easily confirm the effect that the applied laser beam will have on the face sides of workpieces.

[Fig. 9]